

## SMD, QML, and MIL-STD-883 Flows

**SMD/QML:** Devices are processed per the applicable Class Q requirements of MIL-PRF-38535 and the SMD detail requirements and are fully compliant as such.

MIL-STD-883: Devices are tested 100% electrically at -55°C, +25°C, and +125°C per applicable manufacturer's part number data sheet or test program and processed per MIL-STD-883 and are fully compliant as such.

## START

- WAFER TRACEABILITY and DESIGN VERIFICATION (MIL-STD-883/QML)
- > OUTGOING QAINSPECT
- ASSEMBLY HOUSE INCOMING QAINSPECT
- > WAFER SAW and DIE PREP
- > SECOND OPTICAL INSPECTION
- > QALOTACCEPTANCE
- > FRAME ATTACH
- > DIEATTACH
- > DIE ATTACH CURE
- > WIRE BOND
- > THIRD OPTICAL INSPECTION
- > QALOTACCEPTANCE
- Rochester FIELD SOURCE SURVEILLANCE LOT ACCEPTANCE (optional)
- > PRE-SEAL BAKE and VACUUM PRE-WELD BAKE (TO type package only)
- > HERMETIC SEAL / WELD

- TEMPERATURE CYCLING
- > CONSTANT ACCELERATION
- LEAD TRIM (if applicable)
- SOLDER DIP LEAD FINISH and INSPECTION
- MARK and CURE (optional sequence)
- > FINE LEAK SEAL TEST
- > GROSS LEAK SEAL TEST
- VISUAL INSPECTION
- > QALOT ACCEPTANCE
- > SHIP
- > INCOMING QA LOT ACCEPTANCE

- Test Lab INCOMING INSPECT
- > INITIAL ELECTRICAL TEST
- > BURNIN
- ELECTRICAL TEST INTERIM and FINAL
- QUALITY CONFORMANCE INSPECTION Group A
- > FINE/GROSS LEAK
- > EXTERNAL INSPECTION
- QUALITY CONFORMANCE INSPECTION Groups B, C, and D
- > FINAL QA LOT ACCEPTANCE

**FINISH** 

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